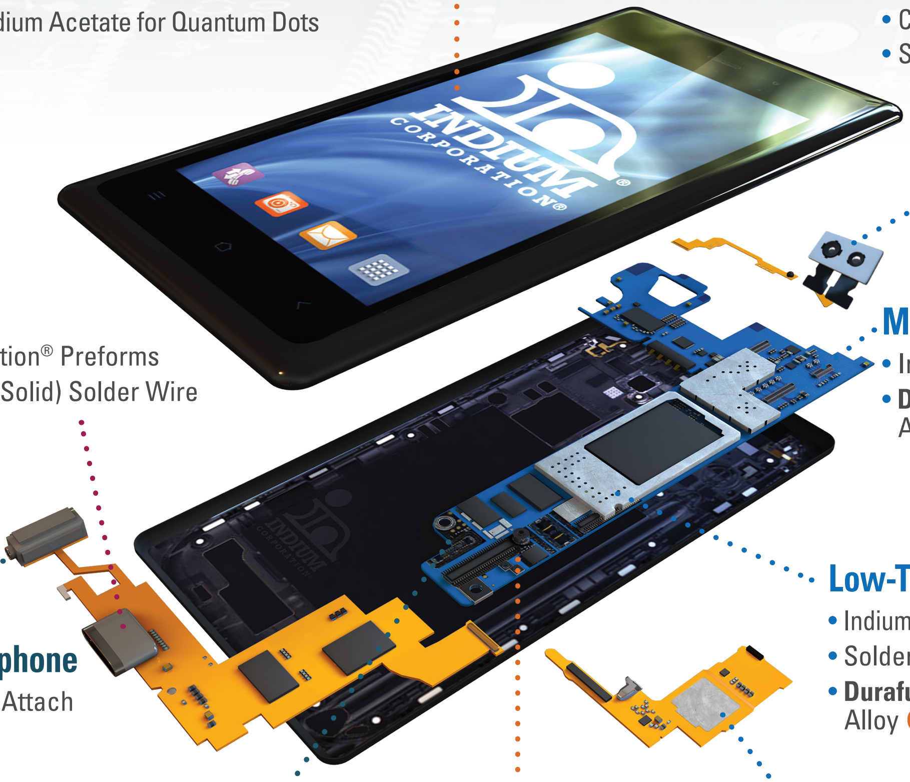
FINER FEATURES—BIGGER CHALLENGES



Display and Touch Sensor

- Indium and Tin Oxide for ITO
- Indium and Gallium Oxide for Oxide TFTs
- Indium Acetate for Quantum Dots

Camera Module

- Indium8.9HF Solder Paste
- Indium5.7LT-1 Solder Paste
- CW-818HF Flux-Cored Wire
- SiPaste® 3.2HF Solder Paste

Connector

- Solder Fortification® Preforms
- Ultrafine (Core/Solid) Solder Wire

Main Logic Board (MLB)

- Indium12.8HF Solder Paste
- **Durafuse™ LT** High-Reliability Alloy NEW

Low-Temperature Shield Attach

- Indium5.7LT-1 Solder Paste
- Solder Fortification® Preforms
- **Durafuse™ LT** High-Reliability Alloy NEW

MEMS Microphone

- NC-SMQ77 Lid-Attach Solder Paste
- **Indium12.8HF** High-Reliability Jetting Paste

System-in-Package (SiP)

- SiPaste® 3.2HF Solder Paste
- WS-446HF Bulb and Flip-Chip Flux

GaAs RF Chips

- Gallium Trichloride

Flexible Printed Circuit (FPC)

- Indium8.9HF Solder Paste
- CW-818HF Flux-Cored Wire
- Core 230-RC (Robotic Soldering) Cored Wire

Materials for Chargers:

- Indium8.9HF Solder Paste
- WF-7745 (VOC-Free) Wave Solder Flux
- WF-9945 Wave Solder Flux
- Core 230-RC (Robotic Soldering) Cored Wire
- CW-818HF Flux-Cored Wire

Contact Tushar Umesh Tike: **tumesh@indium.com**
Learn more: **www.indium.com/mobile**

From One Engineer To Another®

All of Indium Corporation's solder paste and preform manufacturing facilities are IATF 16949:2016 certified. Indium Corporation is an ISO 9001:2015 registered company.

Form No 99940 R0

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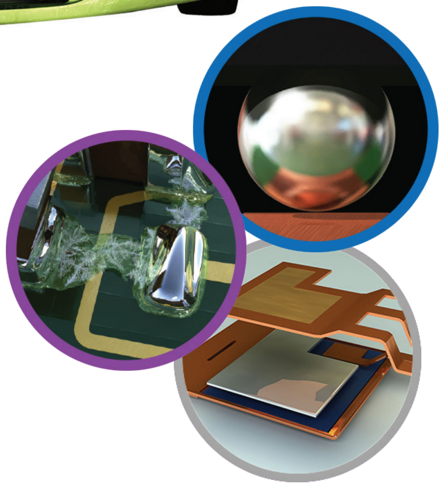
Reliable, Scalable, Proven

No ZERO km Failures

Today over 2 million EVs are on the road with Rel-ion™ electrical, mechanical, and thermal solutions by Indium Corporation

ELECTRICAL



Electrical Continuity

- Eliminating non-wet opens and head-in-pillow defects

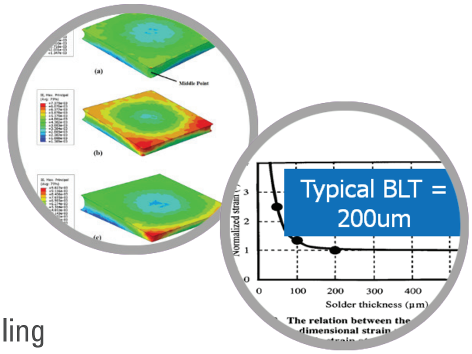
Dendrites/Corrosion

- Meets stricter SIR requirements with rework solutions to pass SIR testings unheated

Leakage Current

- Low alpha particle solution for >650 volt GaN dies

MECHANICAL



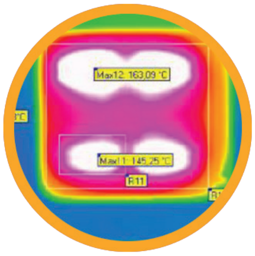
Solder Delamination

- Precision BONDLINE control
- Increased creep resistance
- Increased fatigue resistance

Longer Mission Profiles

- Increased operating temperatures, thermal, and power cycling

THERMAL



Hot Spots

- Voiding reduced, increased CPU/GPU thermal requirements, and materials for power modules/IGBT/DSC modules

Contact Tushar Umesh Tike: **tumesh@indium.com**

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